

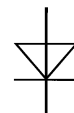
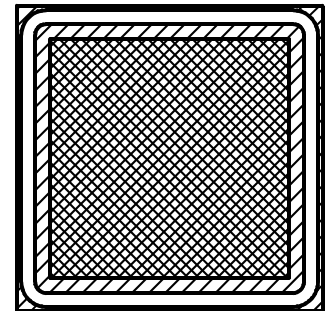
| Absolute Maximum Ratings |                                                  |        |                  |
|--------------------------|--------------------------------------------------|--------|------------------|
| Symbol                   | Conditions <sup>1)</sup>                         | Values | Units            |
| $V_{RRM}$                |                                                  | 1200   | V                |
| $I_{FSM}$                | ( $\geq 8$ bondwires 300 $\mu m$ $\varnothing$ ) |        |                  |
|                          | $t_p = 10$ ms; sin; $T_j = 150$ °C               | 720    | A                |
| $I_t^2$                  | $t_p = 10$ ms; sin; $T_j = 150$ °C               | 2600   | A <sup>2</sup> s |
| Tsolder                  | max. 120 s (transfer)                            | 375    | °C               |
| $T_{vj}, T_{stg}$        | min                                              | - 55   | °C               |
| $T_{vj}, T_{stg}$        | max                                              | + 150  | °C               |

## SEMICELL CAL - Diode Chips<sup>3)</sup>

### SKCD 61C 120 I

7,8 x 7,8 mm; 65 A<sup>4)</sup>; 1200 V

GBCD061



| Characteristics |                                 |      |      |         |            |
|-----------------|---------------------------------|------|------|---------|------------|
| Symbol          | Conditions <sup>1)</sup>        | min. | typ. | max.    | Units      |
| $I_{RM}$        | $T_j = 25$ °C/125 °C; $V_{RRM}$ |      |      | 0,2 / 6 | mA         |
| $V_F$           | $I_F = 75$ A; $T_j = 25$ °C     |      | 2,0  | 2,5     | V          |
|                 | $T_j = 125$ °C                  |      | 1,8  | 2,3     | V          |
| $V_F$           | $I_F = 100$ A; $T_j = 25$ °C    |      | 2,25 |         | V          |
|                 | $T_j = 125$ °C                  |      | 2,05 |         | V          |
| $V_{T(TO)}$     | $T_j = 125$ °C, see Fig. 1      |      | 1,0  | 1,2     | V          |
| $r_T$           | $T_j = 125$ °C                  |      | 11   | 15      | m $\Omega$ |
| $I_{RRM}$       | $I_F = 75$ A; <sup>2)</sup>     |      |      |         |            |
|                 | $T_j = 125$ °C                  |      | 45   |         | A          |
| $Q_{rr}$        | $I_F = 75$ A; $T_j = 25$ °C     |      | 3    |         | $\mu$ C    |
|                 | <sup>2)</sup> $T_j = 125$ °C    |      | 11   |         | $\mu$ C    |
| Tsolder         | 10 min                          |      | 250  |         | °C         |
| Tsolder         | 5 min                           |      |      | 320     | °C         |

| Mechanical Data                                                                                                      |             |    |                 |
|----------------------------------------------------------------------------------------------------------------------|-------------|----|-----------------|
| $A_{tot}$                                                                                                            | total area  | 61 | mm <sup>2</sup> |
| $A_{act.}$                                                                                                           | active area | 44 | mm <sup>2</sup> |
| w                                                                                                                    | weight      | 50 | mg              |
| Supplied on chip carriers (64 units) 102 x 102 x 8 mm<br>or supplied on frames, on request<br>Please contact factory |             |    |                 |

1)  $T_{case} = 25$  °C, unless otherwise specified

2)  $V_R = 600$  V;  $- di_F/dt = 800$  A/ $\mu$ s;

3) CAL = Controlled Axial Lifetime Technology

4) Soldered on DCB ceramic ( $Al_2O_3$ ) 0,4 mm thick  
on a 3 mm copper base plate  $R_{thjc} = 0,5$  K/W  
 $T_{jm} = 150$  °C;  $T_{case} = 80$  °C.

## Features

- Low voltage drop
- low temperature dependence
- Very soft reverse recovery under **all** conditions
- CAL = Controlled Axial Lifetime Technology
- Top side = Al for bonding by aluminum wire
- Bottom = 4 layer metallisation for soldering

## Typical Applications

- Inverse diode for IGBT (in inverter drives)
- Freewheeling diode in brake choppers or step-up choppers with IGBT or MOSFET
- UPS Uninterruptible Power Supplies
- Hybrid circuits for static power converters

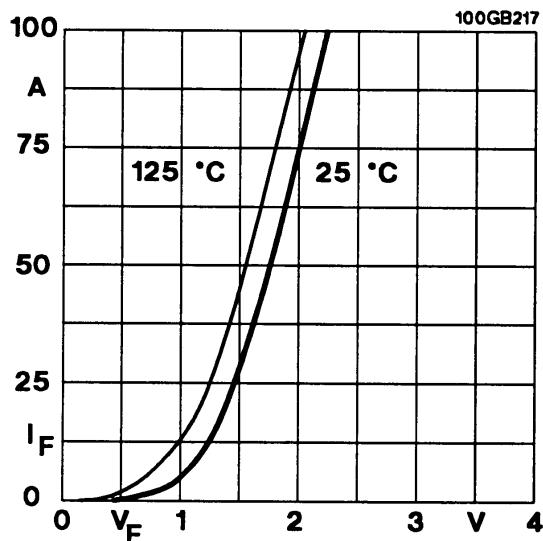


Fig. 1 Typ. CAL diode forward characteristic

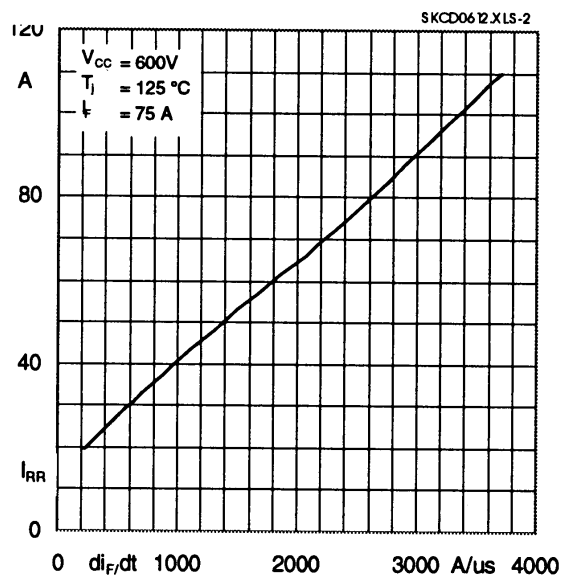


Fig. 2 Typ. peak reverse recovery current  $I_{RR} = f (di_F/dt)$

$T_j = 125\text{ °C}$   
 $di_F/dt = -800\text{ A/μs}$

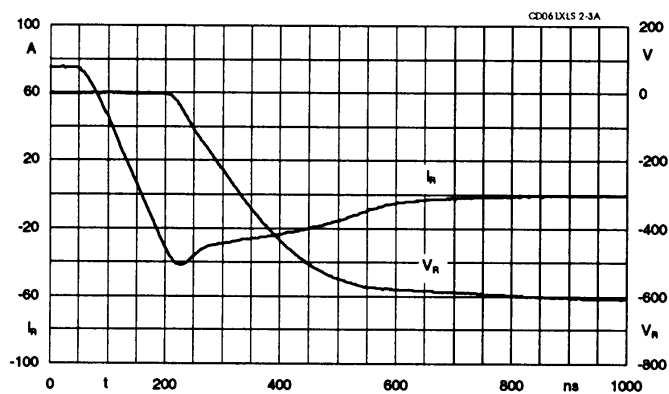


Fig. 3 Typ. diode reverse recovery behaviour  $i = f (t)$

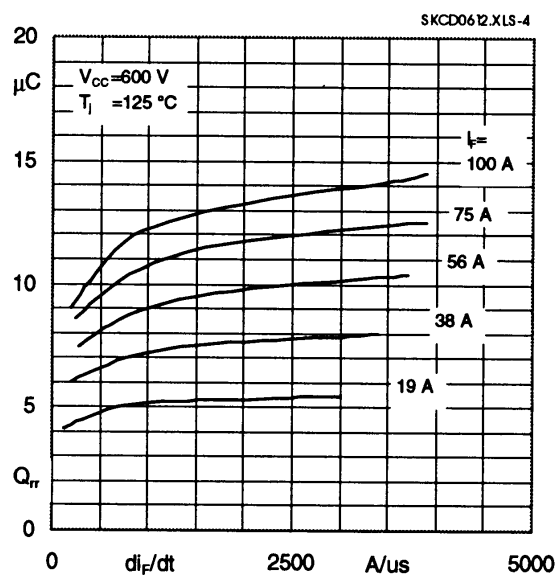


Fig. 4 Typ. reverse recovery charge  $Q_{RR} = f (di_F/dt)$

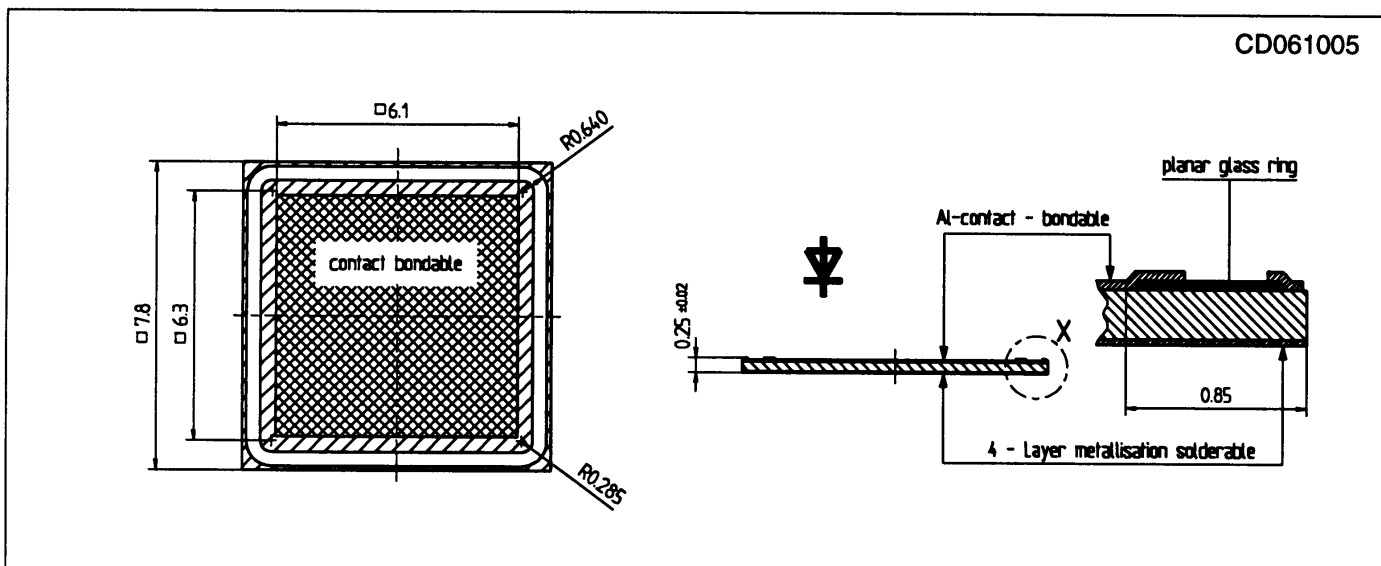


Fig. 5 Mechanical outline (dimensions in mm)